

Test beam analysis on Timepix 3D pixel detector

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An n-type double-sided 3D detector fabricated at CNM bump bonded to a Timepix chip has been tested in a pion and a micro-focused x-ray test beams. The result from both test beams will be shown. The x-ray test beam shows relative detection maps of the 3D pixel device.

The pion test beam results show the absolute detection efficiency, cluster size and resolution for detectors with particles at a range of incident angles from normal to 18 degrees.

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